



Material Content Data Sheet



Sales Product Name		BCR 10PN H6327		Issued		29. August 2013		
MA#		MA001094638						
Package		PG-SOT363-6-1		Weight*		6.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		24	
	noble metal	gold	7440-57-5	0.015	0.24		2392	
	inorganic material	silicon	7440-21-3	0.073	1.17	1.41	11673	14089
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1375	
	non noble metal	copper	7440-50-8	2.869	45.66	45.86	456473	458398
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1633	1633
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4830	
	plastics	epoxy resin	-	0.653	10.38		103848	
	inorganic material	silicondioxide	60676-86-0	2.353	37.43	48.29	374335	483013
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33924	33924
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8943	8943
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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